## AMENDMENT UNDER 37 C.F.R. § 1.116 EXPEDITED PROCEDURE GROUP 2823 PATENT APPLICATION

Inter per RCE filed 8-707

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79041

Group Art Unit: 2823

Examiner: Khiem D. NGUYE

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Confirmation No.: 1863

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

## AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated February 7, 2007, please amend the above-identified application as follows on the accompanying pages. A Petition for a one-month Extension of Time is being concurrently filed, extending the period of response from May 7, 2007 to June 7, 2007.

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